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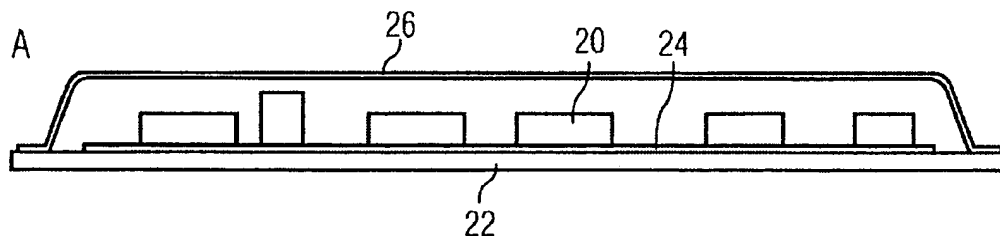
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(54) Title: A METHOD FOR MANUFACTURING AN ELECTRONIC ARRANGEMENT AND AN ELECTRONIC CIRCUIT ARRANGEMENT



(57) Abstract: A method for manufacturing an electronic circuit device in a motor vehicle fuel tank, the method arranging one or more electronic modules on a substrate, and fixating the substrate with respect to a fuel tank wall. To obtain a permanent separation between electronics and fuel, which is easy to implement, and allows to keep the electronics close to the fuel proper, the method according to the invention encapsulates the one or more electronic modules against the fuel by a cap that connects to the substrate whilst forming an encapsulated space that is separated from any fuel or vapour outside the encapsulated space. The electronic modules may provide various different functional principles, e.g. fuel level measuring or demand regulated fuel pump control.